



## AUTOFIL

**AUTOFIL** - MBO range of no-clean solder wire “AUTOFIL” is carefully formulated to confer high activity soldering on various substrates, including, copper, tin/lead, brass and nickel amongst others. Various level of activation are available to suit most oxidised metal surfaces.

- High activity
- Fast soldering
- Low fume
- Low odour
- Low spattering
- Lead-free option available

Alloy	Melting point
Sn60Pb40	183 - 190°C
Sn63Pb37	E - 183°C
Sn50Pb48.5Cu1.5	183 - 215°C
Sn96.5Ag3.5/Sn96Ag4	E - 221°C
Sn99.3Cu0.7	E - 227°C
Pb93.5Sn5Ag1.5	296 - 301°C
Sn95.5Ag3.8Cu0.7	E - 217 C
Sn96.5Ag3.0Cu0.5	217 - 221 C
Sn100	E - 232 C
Others	Contact MBO

### Chemical Characteristics

#### Alloys:

Most alloys conforming to international standards available on request

#### Flux content:

1 - 3 % (nominal). Others available on request

#### Flux type:

Blend of rosin and modified rosin

**Halide content:** See table below

A0	A11
0 %	1.1 %
SMT rework General application	SMT rework & highly oxidised substrates

### Application

MBO “AUTOFIL” range of solder wire confers rapid soldering on copper, tin/lead, brass and nickel. MBO “AUTOFIL” range of solder wire can be used in conjunction with various methods of soldering, such as solder iron, hot air, induction, hot plate and blow torch. When used with a solder iron, it is recommended to use an operating temperature of around 380 - 420°C. Elevated temperatures can be used but some carbonisation of the flux residues may result.

### Residue Removal

Post-soldering residues of MBO “AUTOFIL” range of solder wire can be removed, if required, with commercially available solvents such as alcohols, hydrocarbons, and other propriety cleaners.